

Title (en)

ELECTRICAL CONTACT CONNECTION AND METHOD FOR CREATING ONE SUCH CONTACT CONNECTION

Title (de)

ELEKTRISCHE KONTAKTVERBINDUNG UND VERFAHREN ZUM AUSBILDEN EINER SOLCHEN KONTAKTVERBINDUNG

Title (fr)

LIAISON DE CONTACT ELECTRIQUE ET PROCEDE POUR REALISER UNE TELLE LIAISON DE CONTACT

Publication

**EP 1759439 A1 20070307 (DE)**

Application

**EP 05744312 A 20050525**

Priority

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- DE 102004030784 A 20040625

Abstract (en)

[origin: US2006201934A1] In order to make it possible to produce a secure and permanent contact connection between an electrical conductor made from a soft material, in particular an aluminum conductor, and a contact element made from a harder material, the conductor is encapsulated at least partially in a contact region by an electrically conductive material. The electrically conductive material is harder than the soft material of the conductor. The electrically conductive material is applied with the aid of a thermal spraying process, with the result that there is a pressure-free electrical connection between the soft material and the sprayed-on material. Electrical contact is made with the contact element indirectly via the sprayed-on material. The thermal encapsulation by the spraying in the contact region makes it possible for a reliable electrical contact to be made even in the case of soft materials having a tendency towards cold flow.

IPC 8 full level

**H01R 4/62** (2006.01); **H01R 9/03** (2006.01); **H01R 13/03** (2006.01); **H01R 4/20** (2006.01); **H01R 11/28** (2006.01)

CPC (source: EP US)

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Citation (search report)

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**US 2006201934 A1 20060914**; **US 7282679 B2 20071016**; AT E444578 T1 20091015; CN 100409489 C 20080806; CN 1820393 A 20060816; DE 102004030784 A1 20060119; DE 502005008243 D1 20091112; EP 1759439 A1 20070307; EP 1759439 B1 20090930; ES 2333027 T3 20100216; JP 2008503859 A 20080207; PT 1759439 E 20091113; WO 2006000279 A1 20060105

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